As an early-career Interconnect Qualification Engineer at IBM the IEC YP program through the USNC is an excellent fit for my experience and career goals. Through my position in the Supply Chain Engineering division of IBM Infrastructure, I interface with several of IBM’s key suppliers globally, as well as internally with IBM leaders within the Compliance and Development organizations. Both my work internally with IBM and work with our suppliers positions me well to help contribute to the IEC’s mission to bring global stakeholders together to cooperate on international standards.

Within IBM, I co-chair our Power Cord Council with Senior Technical Staff Member Joe Prisco. This Council brings together Compliance, Development, and Supply Chain individuals from across several divisions to collaborate on problems that directly impact our customers. Most of the cords that are under the purview of the Council follow either IEC 60320 or 60309 standards. IBM ships globally, and I have seen firsthand how the IEC standards, which are followed worldwide, are critical for ensuring that we ship compliant and safe cords to our customers regardless of their location. One of the goals of the council is to push our Developers to lean more on industry standards to aid in sourcing and ensure consistency across the company. Educating the team on the purpose and utility of industry standard specifications is something I am passionate about, and IBM has already seen great benefit by relying more on IEC standards instead of creating more of our own.

When qualifying a new part number, I frequently reference the IEC standards and review 3rd party test reports to confirm the quality of a part. As a qualification engineer, I am highly interested in the process of determining what tests IEC mandates for various technology types and am eager to get the opportunity to observe this process firsthand. The IEC YP program is a great entry point to participating in the standards-writing process.

IBM’s suppliers are on the forefront of development and manufacturing technology. In my role, I interface with leaders from factories worldwide and have learned a lot about how our product is manufactured and many of the challenges that come with manufacturing. Every year IBM brings in key suppliers to present regarding their efforts in key domains such as AI, Sustainability, and Digital Transformation. In particular, the focus on AI has stood out to me in this past year’s presentations. Our suppliers have been quickly moving to implement AI in their development and manufacturing processes, and have implemented impressive innovations in this domain. There is an opportunity and immediate need for standards in relation to this work, and I am very excited by the opportunity to participate through the IEC YP program.

My mentor and nominator for this application, Joe Prisco, is a technical leader at IBM and is highly involved in the IEC. I have seen firsthand how this experience has broadened his knowledge, given him connections throughout the industry, and allowed him to become a leader not only at IBM but in the industry as a whole. I have seen the numerous benefits of IEC involvement, and this opportunity would be a first step for me to become involved with the IEC, which I intend to continue involvement with for the duration of my career.